

IN THE CLAIMS

1. (Currently Amended) A layered thermal component, comprising:
at least one thermal interface component, wherein the thermal interface component comprises at least one rubber compound having at least one terminal hydroxyl group and at least one thermally conductive filler material; and
at least one heat spreader component coupled to the thermal interface component, wherein the combination of the at least one thermal interface component and the at least one heat spreader component is designed to minimize interfacial thermal resistance in the layered thermal component.
2. (Previously Presented) The layered thermal component of claim 1, wherein the at least one thermal interface component comprises a crosslinkable material.
3. (Previously Presented) The layered thermal component of claim 2, wherein the at least one thermal interface component further comprises at least one crosslinker moiety, at least one crosslinking compound or at least one crosslinking resin.
4. (Previously Presented) The layered thermal component of claim 3, wherein the at least one crosslinker moiety, the at least one crosslinking compound or the at least one crosslinking resin comprises an amine resin or an amine-based compound.
5. (Previously Presented) The layered thermal component of claim 1, wherein the at least one rubber compound comprises at least one secondary, tertiary or otherwise internal hydroxyl group.
6. (Previously Presented) The layered thermal component of claim 1, wherein the at least one thermal interface component comprises at least one solder material.
7. (Previously Presented) The layered thermal component of claim 1, wherein the at least one heat spreader component comprises at least one metal or metal-based base material.

Claims 8-17: Canceled.

Honeywell Docket No. H0004275.68586 US - 4018
Buchalter Docket No.: H9925-3405

18. (Previously Presented) A semiconductor component comprising the layered thermal component of claim 1.

Claims 19-20: Canceled.